

Description

The IPD30N03S2L-10 uses advanced trench technology

to provide excellent RDS(ON), low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = 30V I_D =60 A

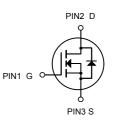
 $R_{DS(ON)} < 9m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch Uninterruptible power supply





N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
IPD30N03S2L-10	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units V	
Vds	Drain-Source Voltage	30		
Vgs	Gate-Source Voltage	Gate-Source Voltage ±20		
I₀@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	60	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	40	А	
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	13.6	А	
I₀@T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	11.4	А	
Ідм	Pulsed Drain Current ²	110	А	
EAS	Single Pulse Avalanche Energy ³	57.8	mJ	
las	Avalanche Current	34	А	
PD@Tc=25°C	Total Power Dissipation ⁴ 41		W	
PD@TA=25°C	Total Power Dissipation ⁴ 2.42		W	
Tstg	Storage Temperature Range -55 to 175		°C	
TJ	Operating Junction Temperature Range -55 to 175		°C	
Reja	Thermal Resistance Junction-ambient (Steady State) ¹	62	°C/W	
Rejc	Thermal Resistance Junction-Case ¹	3.6	°C/W	

N-Channel Enhancement Mode MOSFET

Symbol	mbol Parameter Conditions		Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
∆BVbss/∆Tj	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.027		V/°C
		V _{GS} =10V , I _D =30A		7	9	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =15A		11	14	mΩ
VGS(th)	Gate Threshold Voltage		1.2	1.5	2.5	V
$\bigtriangleup V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient	$-V_{GS}=V_{DS}$, $I_{D}=250 uA$		-5.8		mV/°C
		V _{DS} =24V , V _{GS} =0V , T _J =25°C	=0V , TJ=25°C 1		1	<u> </u>
loss	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA
lgss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		38		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.2	3.5	
Qg	Total Gate Charge (4.5V)			12.6	17.6	
Qgs	Gate-Source Charge			4.2	5.9	nC
Q _{gd}	Gate-Drain Charge			5.1	7.1	
Td(on)	Turn-On Delay Time			4.6	9.2	
Tr	Rise Time			12.2	22	
Td(off)	Turn-Off Delay Time	ID=15A		26.6	53	ns
T _f	Fall Time			8	16	
Ciss	Input Capacitance			1317	1843	
Coss	Output Capacitance			163	228	pF
Crss	Reverse Transfer Capacitance			131	183	P
ls	Continuous Source Current ^{1,5}				55	A
Іѕм	Pulsed Source Current ^{2,5}	$-V_G=V_D=0V$, Force Current			110	A
					1.2	V
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C				
trr	Reverse Recovery Time	I⊧=30A , dI/dt=100A/µs ,		9.2		nS
Qrr	Reverse Recovery Charge	T _J =25°C		2		nC

Electrical Characteristics (TJ=25 °C, unless otherwise noted)

Note :

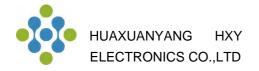
1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =34A

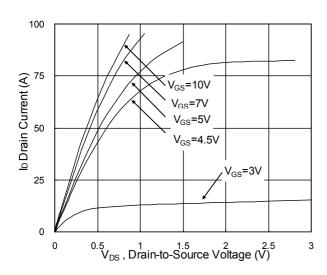
4.The power dissipation is limited by 175°C junction temperature

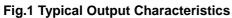
5.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.



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Typical Characteristics





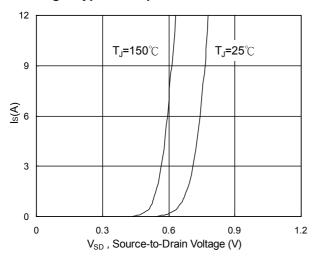


Fig.3 Forward Characteristics of Reverse

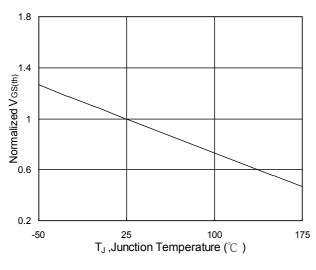


Fig.5 Normalized V_{GS(th)} vs. T_J

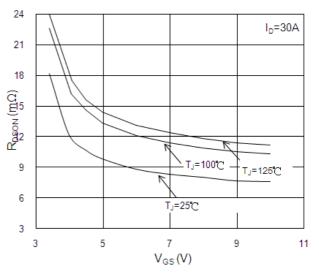


Fig.2 On-Resistance vs. G-S Voltage

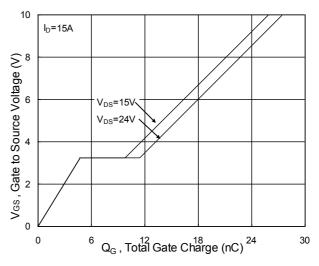


Fig.4 Gate-Charge Characteristics

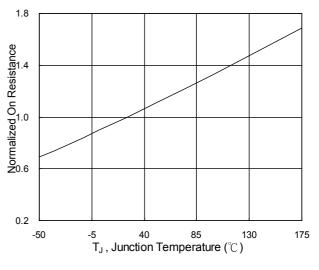
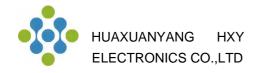


Fig.6 Normalized R_{DSON} vs. T_J



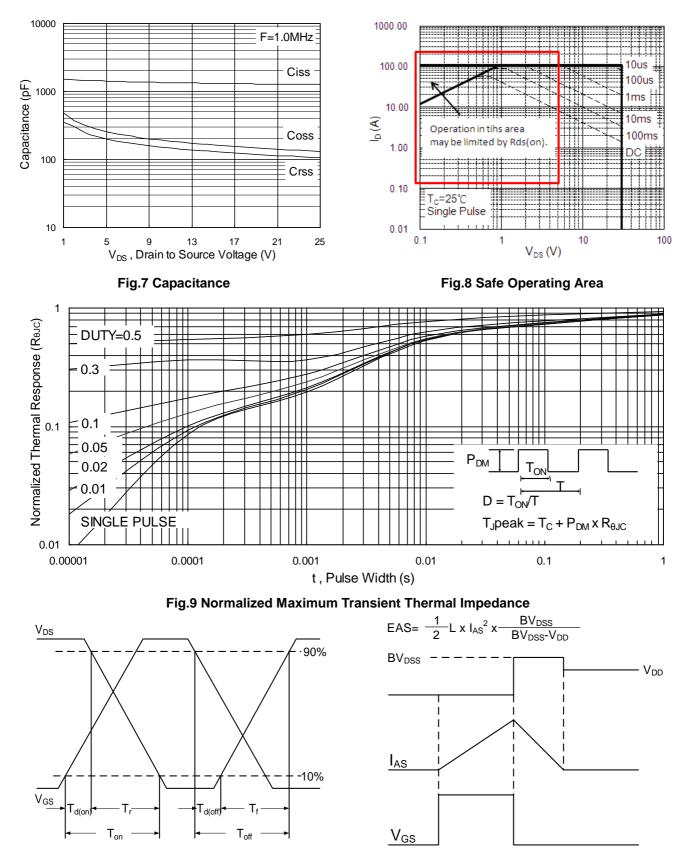
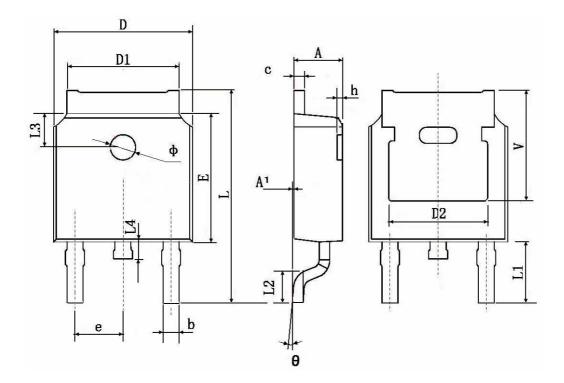


Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



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